

### **Description**

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{\text{DS(ON)}}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

## **Application**

- DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

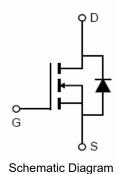
#### **General Features**

- $V_{DS}$  =85V, $I_D$  =120A  $R_{DS(ON)}$ =4.45m $\Omega$  , typical (TO-220)@  $V_{GS}$ =10V  $R_{DS(ON)}$ =4.25m $\Omega$  , typical (TO-263)@  $V_{GS}$ =10V
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating





TO-263

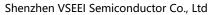


**Package Marking and Ordering Information** 

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST08N042-TC	VST08N042	TO-220C	-	-	-
VST08N042-T3	VST08N042	TO-263	-	-	-

# Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	85	V	
Gate-Source Voltage	Vgs	±20	V	
Drain Current-Continuous	I <sub>D</sub>	120	А	
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	92	А	
Pulsed Drain Current	I <sub>DM</sub>	480	А	
Maximum Power Dissipation	P <sub>D</sub>	150	W	
Derating factor		1.0	W/℃	
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	660	mJ	
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	$^{\circ}$	





# **Thermal Characteristic**

Thermal Resistance, Junction-to-Case (Note 2)	R <sub>0</sub> JC	1.0	°C/W
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Electrical Characteristics (T<sub>C</sub>=25°Cunless otherwise noted)

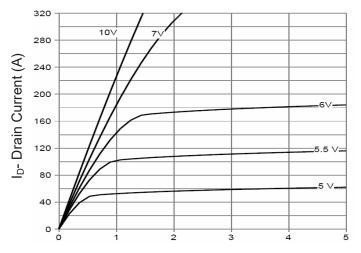
Parameter	neter Symbol Condition		on	Min	Тур	Max	Unit
Off Characteristics				•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA		85		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =85V,V <sub>GS</sub> =0V		-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V		-	-	±100	nA
On Characteristics (Note 3)				· I			
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA		2.0	3.0	4.0	V
Dunin Course On Chata Basistan	-	V <sub>GS</sub> =10V, I <sub>D</sub> =60A	TO-220	-	4.45	4.8	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>		TO-263		4.25	4.8	mΩ
Forward Transconductance	<b>g</b> FS	$V_{DS}=5V,I_{D}=$	<sub>DS</sub> =5V,I <sub>D</sub> =60A		65	-	S
Dynamic Characteristics (Note4)				•			
Input Capacitance	C <sub>lss</sub>	- V <sub>DS</sub> =40V,V <sub>GS</sub> =0V, - F=1.0MHz		-	3780	-	PF
Output Capacitance	Coss			-	740	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	30	-	PF
Switching Characteristics (Note 4)					•		
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD}$ =40V, $I_{D}$ =60A $V_{GS}$ =10V, $R_{G}$ =1.6 $\Omega$		-	21	-	nS
Turn-on Rise Time	t <sub>r</sub>			-	61	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>			-	40	-	nS
Turn-Off Fall Time	t <sub>f</sub>			-	12	-	nS
Total Gate Charge	Qg	\/ -40\/.	CO A	-	71	-	nC
Gate-Source Charge	Q <sub>gs</sub>	- V <sub>DS</sub> =40V,I <sub>D</sub> =60A, - V <sub>GS</sub> =10V		-	21		nC
Gate-Drain Charge	$Q_{gd}$			-	22		nC
Drain-Source Diode Characteristics				•	•		
Diode Forward Voltage (Note 3)	$V_{SD}$	V <sub>GS</sub> =0V,I <sub>S</sub> =60A		-		1.2	V
Diode Forward Current (Note 2)	Is			-	-	120	Α
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = I <sub>S</sub>		-	67	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>		-	137	-	nC

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25  $^{\circ}\text{C}$  ,V\_DD=40V,V\_G=10V,L=0.5mH,Rg=25 $\Omega$

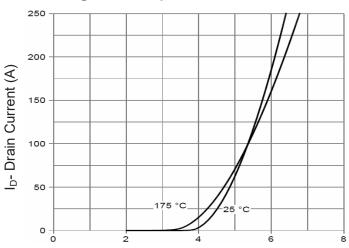


### **Typical Electrical and Thermal Characteristics**



Vds Drain-Source Voltage (V)

**Figure 1 Output Characteristics** 



Vgs Gate-Source Voltage (V)

**Figure 2 Transfer Characteristics** 

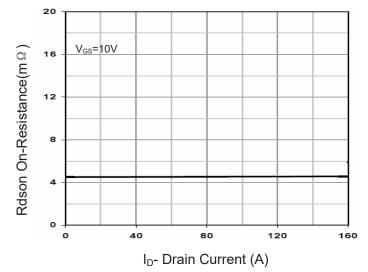
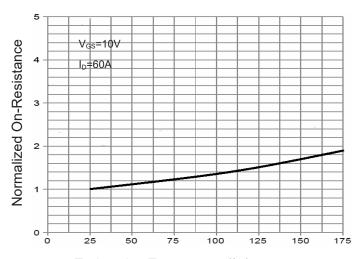
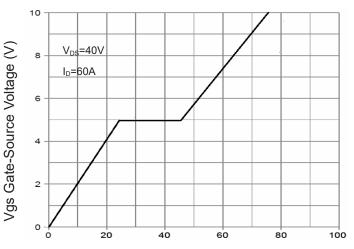


Figure 3 Rdson- Drain Current

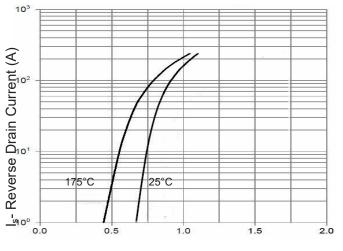


T<sub>J</sub>-Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



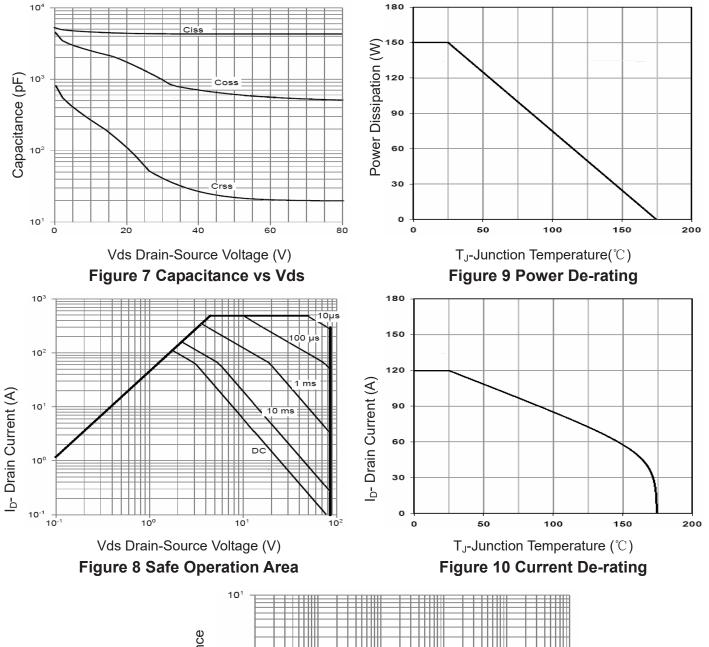
Qg Gate Charge (nC)
Figure 5 Gate Charge

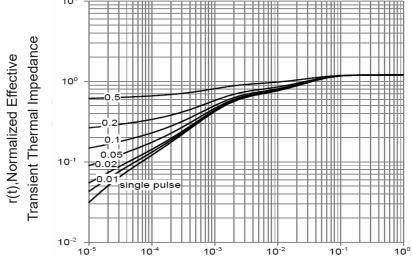


Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward







**Figure 11 Normalized Maximum Transient Thermal Impedance** 

Square Wave Pluse Duration(sec)